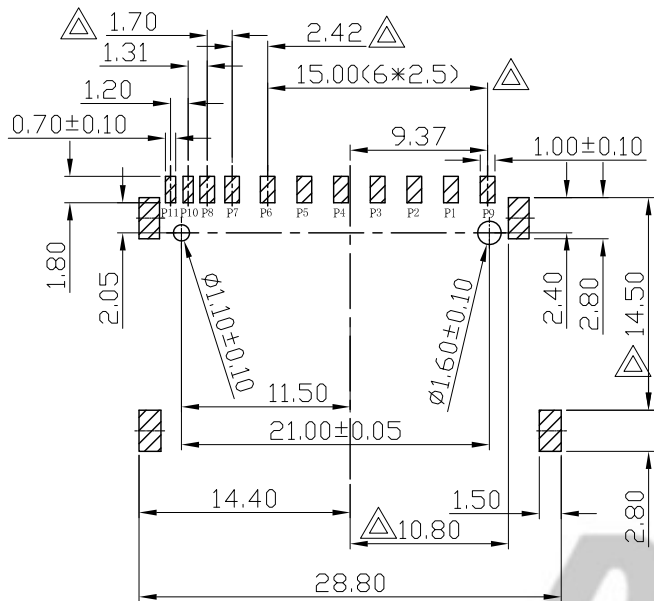


Rev.	ECN Number	Description	Drawn
1	CH13070184	初版發行	hewangke_07/22'13
2	EH15010272	依照客戶要求修改LAYOUT尺寸	Renxiang_01/30'15
3	EH15080097	依照客戶要求取消LATCH:STAINLESS STEEL	Yong Zhang_08/21'15

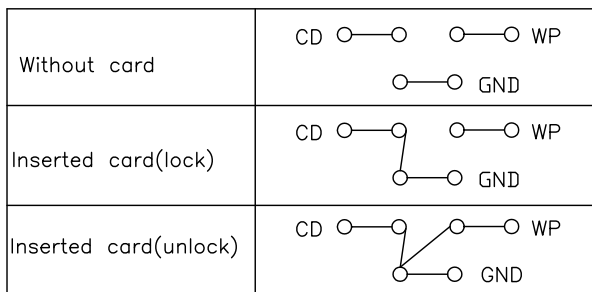


GENERAL TOLERANCE		SCALE	ORIGINAL DRAWN	DATE	DWG. NO.	TITLE	REV.
XX. ±	XXX. ±	N/A	Yong Zhang	08/21'15	600-0000-1278	CUSTOMER_DRAWING	3
X. ± 0.35	.XXX ±	UNIT	CHECK	DATE			PARTS NO.(INTENDED USE)
.X ± 0.25	X.* ± 3°	MM			CS1S-06*.*.*	1/4	
.XX ± 0.20	.X.* ± 2°	SIZE	APPROVE	DATE			
		A4	Qinghua Deng	08/21'15			



PCB LAYOUT  
TOLERANCE: ±0.05

PAD AREA



PIN NO.	SD NAME
P1	CD/DAT3
P2	CMD
P3	VSS
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	DAT2
P10	C/D
P11	W/P

SPECIFICATION:

1.All Dimensions are in Millimeters.

2.Material:

Housing:High temperature thermoplasticul 94 V-0 .

Contact:Copper alloys

Plating:nickel

Contact area:gold over nickel

3.Dimension shall be inerpreted per"ansi Y14.5M-1994"

4.Durability: 10000 cycles MIN.

5.Contact retention force: 150g MIN. per contact.

6.Electrical characteristics:

SD Pin Contact Resisitance: 60m Ohm max initial

Dielectric Withstanding Voltage:

500VAC Max With 1 Minute

7.Insulation Resisitance:1000 M Ohm Min

8.Current Rating: 0.5 A AC/DC Max.

Rated Valtage : 30 V RMS Min.

9. Operating Temperature: -25°~+85°

10 Storage Temperature:-40°~+85°

11.Harmful Material Should Be Compliant To "ROHS" Standrads.

12. Date code:xxxx means years/monthes/days/product line.

13.Product number :

Card      C      S      1      S - 06 \* - \* - \*

SD card      S      1      S - 06 \* - \* - \*

Single card      1      S - 06 \* - \* - \*

S: Standard type      S - 06 \* - \* - \*

Series No.      S - 06 \* - \* - \*

Plating code

1: gold flash plating on contact area  
Matte TIN plating on solder area

2: 3u" gold plating on contact area  
Matte TIN plating on solder area

3: 5u" gold plating on contact area  
Matte TIN plating on solder area

4: 10u" gold plating on contact area  
Matte TIN plating on solder area

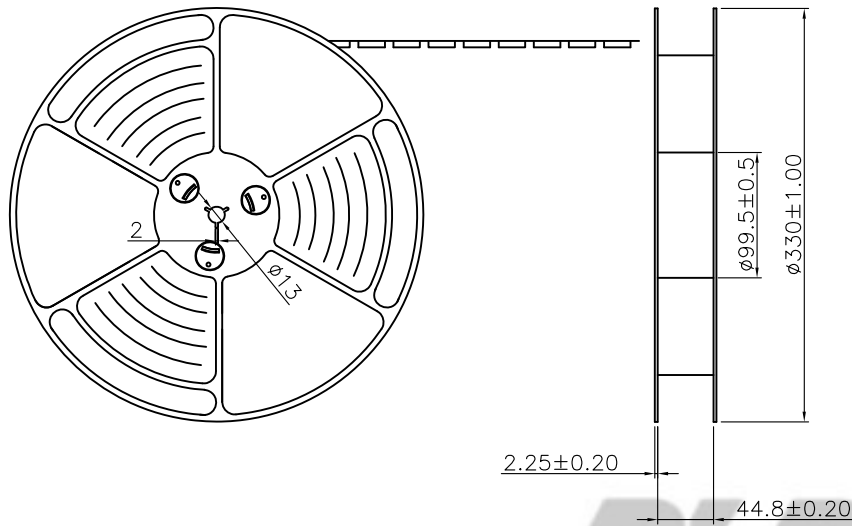
5: 15u" gold plating on contact area  
Matte TIN plating on solder area

D: With dummy card  
N: Without dummy card

H: Halogen free  
N: With halogen



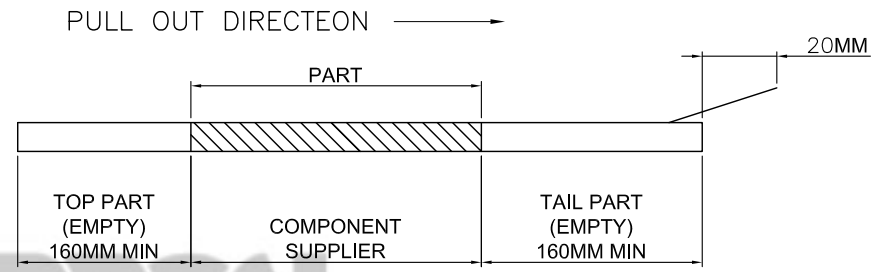
GENERAL TOLERANCE		SCALE	ORIGINAL DRAWN	DATE	DWG. NO.	TITLE	REV.
XX. ±	XXX. ±	N/A	Yong Zhang	08/21'15	600-0000-1278	CUSTOMER_DRAWING	3
X. ± 0.35	.XXX ±	UNIT	CHECK	DATE			PARTS NO.(INTENDED USE)
.X ± 0.25	X.* ± 3°	MM	APPROVE	DATE	CS1S-06*.*	2/4	
.XX ± 0.20	.X* ± 2°	SIZE	Qinghua Deng	08/21'15			



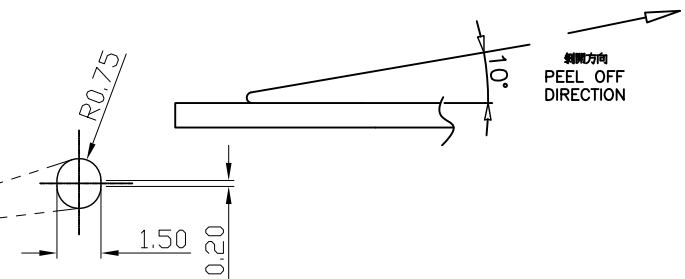
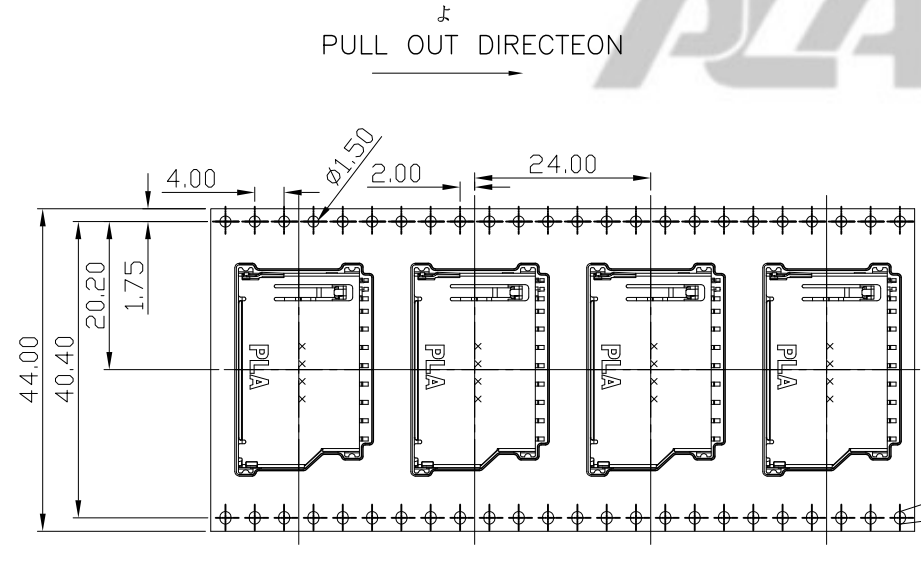
NOTES

1. 每捲包裝數量及每箱裝箱數量如下表格。  
 Packing q'ty of each reel & carton as below table shown.

2. 帶子引導長度  
 Lead tape length



3. 上帶剝力力為：0.1~1.3 N(10.2gf~130gf)  
 Peeling off force of top tape: 0.1~1.3N (10.2gf~130gf)  
 出貨' 運輸過程中一定注意：  
 This requirement should be applied at shipment  
 卷帶在運輸過程中不能散開  
 Peeling off should not be allowed during transportation



GENERAL TOLERANCE		SCALE	N/A	ORIGINAL DRAWN	Yong Zhang	DATE	08/21'15	DWG. NO.	600-0000-1278	TITLE	CUSTOMER_DRAWING	REV.	3
XX. ±	XXX. ±	UNIT	MM	CHECK		DATE		PARTS NO.(INTENDED USE)	CS1S-06*.*.*			SHEET	3/4
X. ± 0.35	.XXX ±	SIZE	A4	APPROVE	Qinghua Deng	DATE	08/21'15						
.X ± 0.25	X.* ± 3°												
.XX ± 0.20	.X* ± 2°												

